

ABSTRACT OF THE DISCLOSURE

A composition for sealing a semiconductor device contains polyphenylene sulfide wherein a line expansion coefficient at 150°C to 200°C is 4.75×10^{-5} [1/°C] or less, a line thermal expansion coefficient at 80 to 130°C is 6.0×10^{-5} [1/°C] or less, and a line expansion coefficient ratio between the flow direction and a normal direction of the flow direction is 0.55 or more.